

DATE	NOTE	VERSION
02-24-2025	Initial Release	Proto
03-12-2025	Layout Changes	Proto

BOARD CHARACTERISTICS

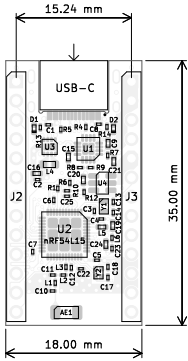
Copper Layer Count:	4	Board Thickness:	1.1382 mm
Board overall dimensions:	18.0000 mm x 35.0000 mm		
Min track/spacing:	0.1000 mm / 0.0900 mm	Min hole diameter:	0.2000 mm
Copper Finish:	None	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

STACKUP

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	1080	0.0764 mm	Not specified	3.7	0.02
In1.Cu	copper		0.0152 mm		1	0
Dielectric	core	FR4	0.865 mm	Not specified	4.5	0.02
In2.Cu	copper		0.0152 mm		1	0
Dielectric	prepreg	1080	0.0764 mm	Not specified	3.7	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

IMPEDANCE TABLE

IMPEDANCE	REF. LAYER	TYPE	TRACE / SPACE
90R	In1 / In2	DP	0.102 mm / 0.1mm
50R	In1 / In2	SE	0.115 mm



<b>BB Designs</b>		
Sheet: Black And White TOP		
File: nrf54_promicro.kicad_pcb		
<b>Title: nRF54 ProMicro</b>		
Size: A4	Date: 2025-03-12	Rev: Proto
KiCad E.D.A. 9.0.0		Id: /1

